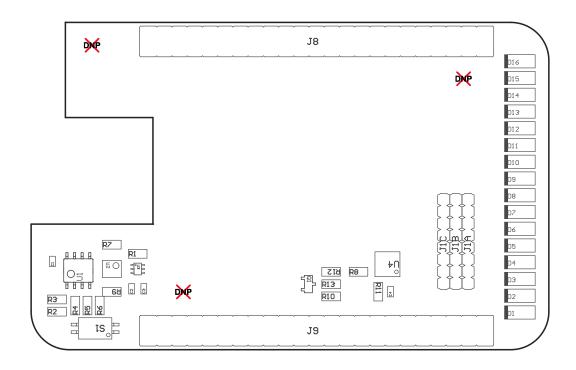
- ZZ1 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZZ ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ3 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE

BOARD #: TIDA-00560

REV: E1

SUN REU: Not In VersionControl

TID #: TIDA-00560

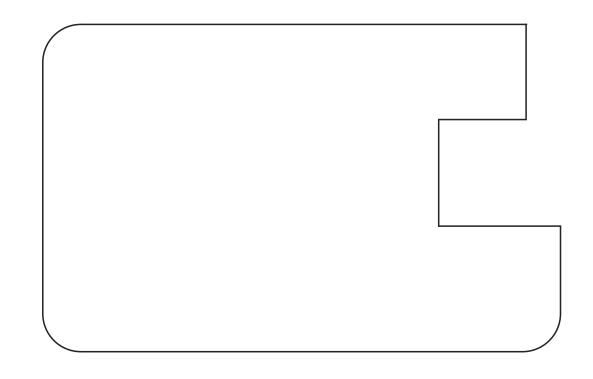
PLOT NAME = Top Assembly Drawing

GENERATED

: 6/18/2015

11:26:12 AM

TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE

BOARD #: TIDA-00560

REV: E1

SUN REV: Not In VersionControl

TID #: TIDA-00560

PLOT NAME = Bottom Assembly Drawing

GENERATED

: 6/18/2015

11:26:14 AM

TEXAS INSTRUMENTS

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